Abstracts

Resonant coupling type microstrip line interconnect using a bonding ribbon and dielectric pad

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M. Hotta, Yongxi Qian and T. Itoh. "Resonant coupling type microstrip line interconnect using a bonding ribbon and dielectric pad." 1998 MTT-S International Microwave Symposium Digest 98.2 (1998 Vol. II [MWSYM]): 797-800.

Resonant coupling type microstrip line interconnects using a bonding ribbon and dielectric pad have been designed and fabricated. The basic concept of this interconnect is the LC serial resonance of the pad capacitor and ribbon inductor. Both numerical simulation and experiment reveal low return loss and high efficiency connection at the predicted resonant frequency region, which can be readily shifted to higher frequencies by tuning the structural parameters. Furthermore, improvement in bandwidth of the interconnect is demonstrated by using a pad with higher dielectric constant.

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